

IN THE CLAIMS

Claim 1 (**currently amended**). An adhesive sheet ~~composed~~ formed of a blend of a rubber S1 and a thermoplastic T2,

- a) the blend being microphase-separated, and
the blend possessing
- b) ~~the blend possessing~~ at least two softening temperatures, at least one softening temperature being greater than 65°C and less than 125°C,
- c) a G' at 23°C, as measured by test method A, of greater than 10⁷ Pas,
- d) a G'' at 23°C, as measured by test method A, of greater than 10⁶ Pas,
- e) and a crossover, as measured by test method A, of less than 125°C.

Claim 2 (**currently amended**). The adhesive sheet of claim 1, ~~characterized in that~~
wherein the rubber is a synthetic rubber.

Claim 3 (**currently amended**). The adhesive sheet of claim 2, ~~characterized in that~~
wherein said synthetic rubbers rubber S1 used are is selected from the group consisting of polyvinyl butyral, polyvinyl formal, nitrile rubbers, nitrile-butadiene rubbers, hydrogenated nitrile-butadiene rubbers, polyacrylate rubbers, chloroprene rubbers, ethylene-propylene-diene rubbers, methyl-vinyl-silicone rubbers, fluorosilicone rubbers, tetrafluoroethylene-propylene copolymer rubbers, butyl rubbers; and styrene-butadiene rubbers.

Claim 4 (**currently amended**). The adhesive sheet of claim 3, ~~characterized in that the~~
wherein said synthetic rubber is a nitrile rubber.

Claim 5 (**currently amended**). The adhesive sheet of claim 4, ~~characterized in that~~
wherein

- a) the nitrile rubber possesses a softening temperature of -80°C to 0°C
- b) the thermoplastic possesses a softening temperature of 65°C to 125°C
- c) the nitrile rubber is insoluble in the thermoplastic.

Claim 6 (**currently amended**). The adhesive sheet of ~~at least one of the preceding claims, characterized in that~~ claim 1, wherein said adhesive sheet is the layer

~~thickness is~~ between 10 and 100 μm thick, ~~with particular preference between 30 and 80 μm .~~

Claim 7 (currently amended). The adhesive sheet of ~~at least one of the preceding claims, characterized in that the thermoplastics T2 are particularly preferably~~ claim 1, wherein the thermoplastic T2 is selected from the ~~groups group~~ consisting of copolyamides, polyethyl-vinyl acetates, polyvinyl acetates, polyolefins, polyurethanes, and copolyesters.

Claim 8 (cancelled).

Claim 9 (currently amended). The adhesive sheet of ~~at least one of the preceding claims, characterized in that reactive resins used additionally comprise~~ claim 1, wherein, in addition to said rubber S1 and said thermoplastic T2, said blend further comprises a reactive resin selected from the group consisting of epoxy resins, ~~and/or~~ phenolic resins, ~~and/or~~ novolak resins and combinations thereof.

Claim 10 (currently amended). ~~The use of an adhesive sheet of at least one of the preceding claims~~ A method for bonding polyimide-, polyester- or epoxy-based chip modules ~~and on PVC, ABS, PET, PC, PP or PE card bodies~~ which comprises bonding said chip modules on said card bodies with the adhesive sheet of claim 1.

Claim 11 (currently amended). A method for producing a heat-activable adhesive tape, ~~characterized in that an adhesive sheet of claims 1 to 9 is coated~~ which comprises coating the adhesive sheet of claim 1 onto a release paper or a release film.

Claim 12 (currently amended). The method of claim 11, ~~characterized in that the heat-activable~~ wherein said adhesive tape is die-cut.

Claim 13. ~~The method of at least one of claims 11 and 12, characterized in that the heat-activable adhesive tape is processed with~~ A method for implanting a chip module in a card body, which comprises implanting said chip module in said card body with a heat activable adhesive tape comprised of the adhesive sheet of claim 1 coated onto a release paper or release film, and

an implanter having an implanting die at an implanting die temperature of 150°C.

Claim 14 (new). The adhesive sheet of claim 6, wherein said thickness is between 30 and 80 μm .